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Jean-Charles Souriau is a scientist leader in the field of wafer-level packaging for more than 20 years at CEA-Leti, Grenoble, France. He has worked at the Electronics and Information Technology Laboratory, French Atomic Energy Commission, Micro and Nanotechnologies Campus. Jean-Charles Souriau received his Ph.D. in Physics from the University of Grenoble (France) in 1993. His areas of expertise are wafer level packaging, heterogeneous integration and 3D integration. He is a Senior Member of the IEEE and chair of the French Chapter of the IEEE Electronic Packaging Society. He is also on the French board of IMAPS France. He has published more than 45 papers in conferences and scientific journals and has 24 patents pending.